

Supporting Information for:

Sintering Copper nanoparticles with photonic additive for printed conductive patterns by intense pulsed light

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1. Thermogravimetric analysis of PVP.
2. UV-vis absorbance spectrum comparison of various composition.
3. SEM images of sintered Cu/CuO film with different sintering intensity.

Figure S1

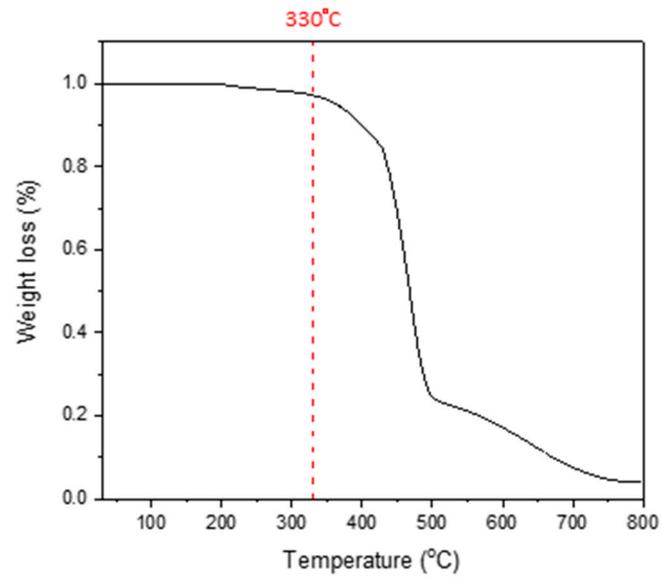


Figure S1 Thermogravimetric analysis of PVP.

Figure S2

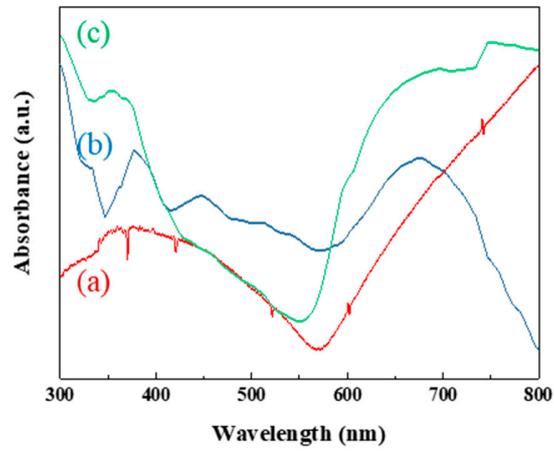


Figure S2. UV-vis absorbance spectrum comparison of (a) CuNP, (b)CuONPs and (c) CuONP/CuNP mixture with a weight ratio of 1/80.

Figure S3

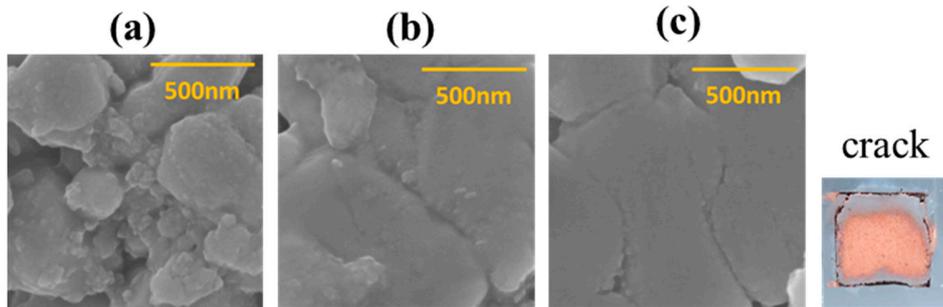


Figure S3. SEM images of sintered Cu/CuO film with sintering intensity at (a) $2.36\text{J}/\text{cm}^2$, (b) $3.08\text{ J}/\text{cm}^2$ and (c) $3.23\text{ J}/\text{cm}^2$.